



BACKGROUND

Introduction and Summary

We apply resonant elastic x-ray scattering (REXS) in a to extract the cross-sectional profile of patterned resists before they have been developed (i.e., latent image). We show how the difference in chemistry induced by the exposure and baking steps can produce enough scattering contrast at certain X-ray energies near a resonant absorption edge in order to provide a 3D latent image profile of the pattern with sub-nanometer resolution. In one case, we explain how latent images were acquired on PMMA and CAR resists by applying REXS near the Carbon K-edge. The reconstruction of this profile provides morphological information that can be compared with the final profiles obtained after development, but the REXS chemical contrast mechanism itself may also shed insight into the chemical nature of the exposure. We elaborate on the impact of the measurement itself (i.e. beam damage) on the resulting pattern morphology as well as how this approach may be applied across other types of resists. Altogether, this information can be used to shed light on the effect that various development and exposure conditions may have on the final resist features that are critica to modern lithography.



Resonant X-Ray Scattering Fundamentals



- Scattering contrast enhanced by tuning incident x-ray energy to a given element's absorption edge
- Enables chemically sensitive xray scattering techniques
- X-ray polarization control can provide molecular orientation.

Combines dispersion, δ , with resonance absorption, β , to enable a chemically-sensitive morphological probe

ALS Resonant Soft X-Ray Scattering (RSoXS) Beamline

RSoXS Endstation Capabilities

- Spacious chamber (~1 m³)
- Resolution $E/\Delta E \le 4000$
- Full polarization control
- High vacuum compatible (~10⁻⁸ Torr)
- 1D detector (photodiode, CEM)
- 2D detector (PI-MTE In-Vacuum Camera, 2048 x 2048, 13 µm pixel)
- Motorized X, Y, Z motion for sample and CCD
- Sample-detector distance: 25 mm to 175 mm
- Sample exchange turnaround time < 1 hour
- 1000:1 suppression of higher order x-rays
- Three sets of slits for parasitic scattering
- <u>Large q-range</u>: 0.002-3 nm⁻¹ at 280 eV; 0.006-10 nm⁻¹ at 1000 eV
- XAS modes in Transmission (Bulk-sensitive), Total Electron Yield (1-20 nm probe depth), and Partial Fluorescence Yield (50-200 nm probe depth)



Rotation in Transmission and Reflection (GI) Configurations for **3-D Reconstructions**

Soft X-ray Scattering Beamline Reaches 160-1300 eV

BERKELEY LAB

Assessing the Impact of Latent Imaging of Resists via **Grazing Incidence Resonant X-ray Scattering**

Isvar Cordova,^{a,b} G. Freychet,^b L. Long,^c S. Dhuey, A. Hexemer, C. Wang,^b P. Naulleau^a Advanced Light Source, Lawrence Berkeley National Laboratory, Berkeley CA 94720 Center for X-ray Optics, Materials Science Division, Lawrence Berkeley National Laboratory, Berkeley CA 94720 University of California at Berkeley, Berkeley, CA 94720

LATENT IMAGING OF EUV RESISTS

Grazing Incidence REXS for Latent Imaging of EUV Resist



- studies of resists on **native thick substrates** • Scattering contrast due to **resonance is only** observed for certain x-ray energies near the
- carbon edge (i.e. ~ 283 eV & 286 eV) Resonant scattering scattering gives contrast due
 - variance matrix adaptatior to distribution of chemistry buried within resist evolutionary strategy (CMAES **GIREXS Enables Extraction of Latent Chemical (Carbon) Profile from CAR Resists on Standard Silicon Substrates**



















Undeveloped PMMA Resist at Oxygen Edge with 20 nm Pitch (below lithographic limit)



